

Features

- High Density Cell Design for Ultra Low $R_{DS(ON)}$
- Trench Power LV MOSFET Technology
- High Speed Switching
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

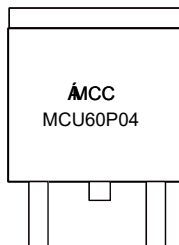
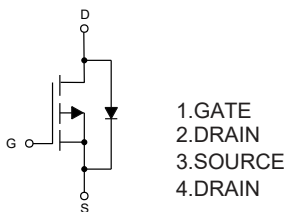
- Operating Junction Temperature Range: -55°C to $+150^{\circ}\text{C}$
- Storage Temperature Range: -55°C to $+150^{\circ}\text{C}$
- Thermal Resistance: 1.14°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain -Source Voltage	V_{DS}	-40	V
Gate -Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	-60	A
Drain Current-Pulsed	I_{DM}	-200	A
Single Pulsed Avalanche Energy(Note2)	E_{AS}	220	mJ
Power Dissipation	P_D	110	W

Note:

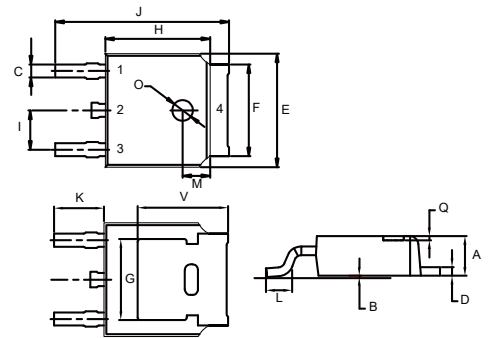
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. EAS Condition: $V_{DD}=-40\text{V}$, $L=1\text{mH}$, $V_G=-10\text{V}$, $T_J = 25^{\circ}\text{C}$

Internal Structure and Marking Code



P-Channel MOSFET

DPAK



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	0.087	0.094	2.20	2.40	
B	0.000	0.005	0.00	0.13	
C	0.026	0.034	0.66	0.86	
D	0.018	0.023	0.46	0.58	
E	0.256	0.264	6.50	6.70	
F	0.201	0.215	5.10	5.46	
G	0.190		4.83		TYP.
H	0.236	0.244	6.00	6.20	
I	0.086	0.094	2.18	2.39	
J	0.386	0.409	9.80	10.40	
K	0.114		2.90		TYP.
L	0.055	0.067	1.40	1.70	
M	0.063		1.60		TYP.
O	0.043	0.051	1.10	1.30	
Q	0.000	0.012	0.00	0.30	
V	0.211		5.35		TYP.

ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-40			V
Gate-Threshold Voltage ^(Note3)	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.2	-1.8	-2.8	V
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 25V, V_{DS} = 0V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -40V, V_{GS} = 0V$			-1	μA
Drain-Source On-Resistance ^(Note3)	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-20A$		6	8	m Ω
		$V_{DS}=-4.5V, I_D=-18A$		10	12	
Gate Resistance	R_g	f=1MHz, Open Drain		14		Ω
Dynamic Characteristics^(Note4)						
Input Capacitance	C_{iss}	$V_{DS}=-20V, V_{GS}=0V, f=1MHz$		5235		pF
Output Capacitance	C_{oss}			490		
Reverse Transfer Capacitance	C_{rss}			430		
Switching Characteristics^(Note4)						
Total Gate Charge	Q_g	$V_{DS}=-20V, V_{GS}=-10V, I_D=-20A$		97		nC
Gate-Source Charge	Q_{gs}			22		
Gate-Drain Charge	Q_{gd}			22		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-20V, V_{GS}=-10V, I_D=-20A, R_{GEN}=2\Omega$		11		nS
Turn-on Rise Time	t_r			55		
Turn-off Delay Time	$t_{d(off)}$			115		
Turn-off Fall Time	t_f			245		
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note3)	V_{SD}	$V_{GS}=0V, I_S=-20A$			-1.2	V
Diode Forward Current ^(Note5)	I_S				-60	A
Reverse Recovery Time	t_{rr}	$T_J=25^\circ C, I_F=-20A, di/dt=-100a/us^{(Note2)}$		31		nS
Reverse Recovery Time	Q_{rr}			20		nC

Note:

3. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by Design, Not Subject to Production.
5. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Curve Characteristics

Fig. 1 - Typical Output Characteristics

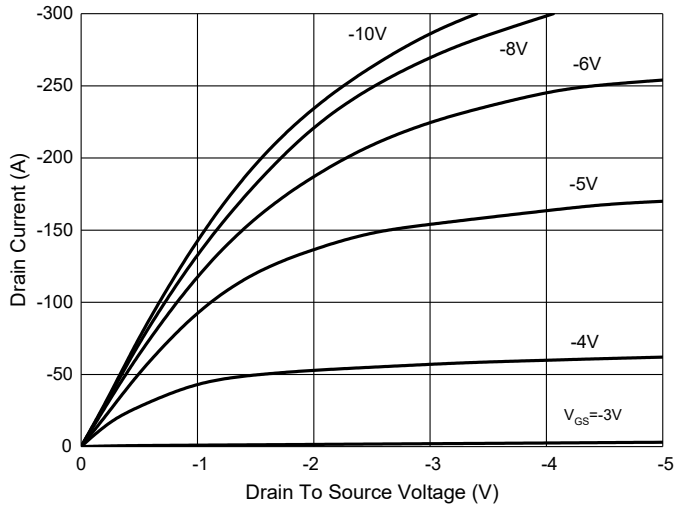


Fig. 2 - Transfer Characteristics

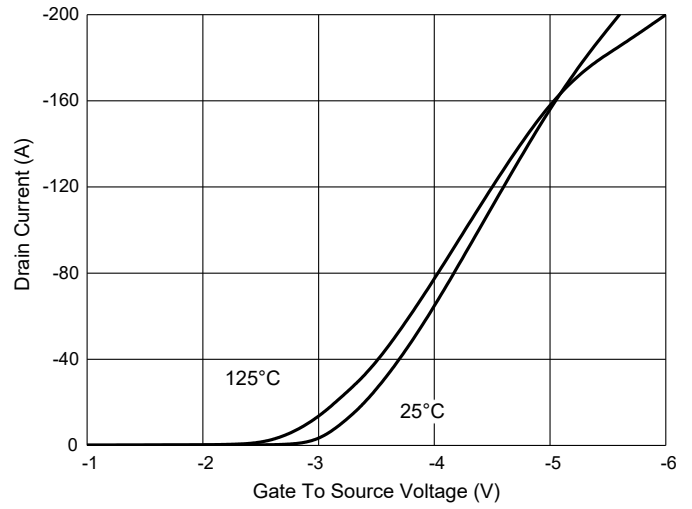


Fig. 3 - $R_{DS(ON)} - I_D$

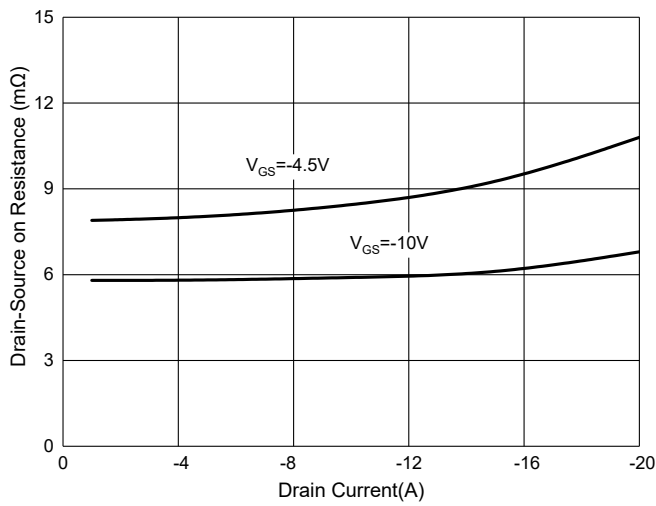


Fig. 4 - Normalized On Resistance Characteristics

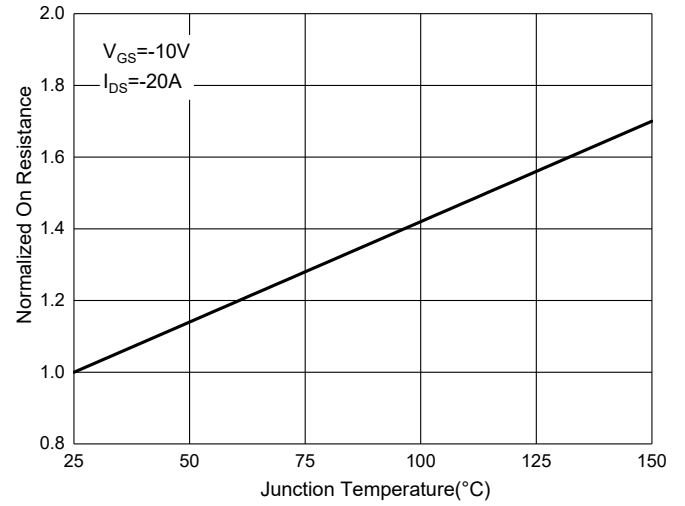


Fig. 5 - Capacitance Characteristics

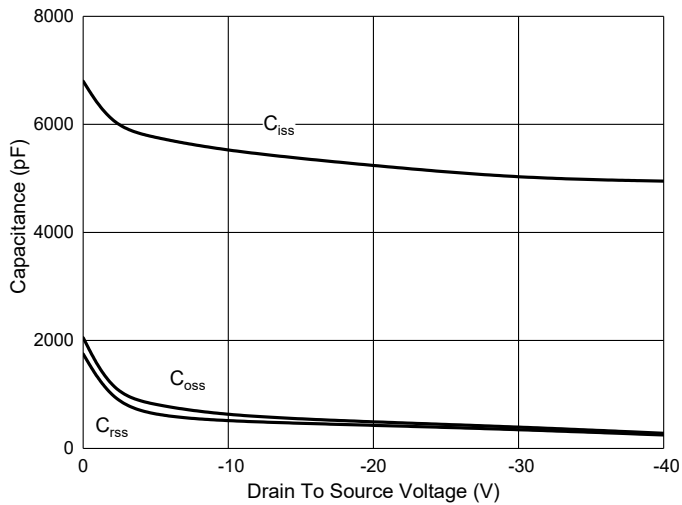
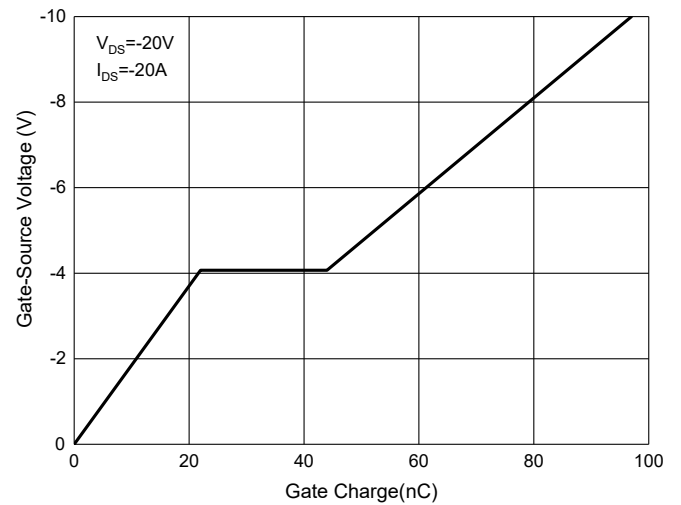


Fig. 6 - Gate Charge



Curve Characteristics

Fig. 7 - Safe Operation Area

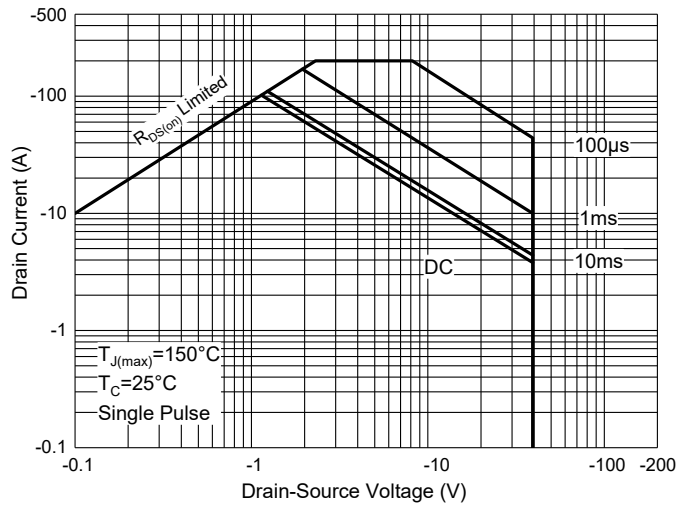
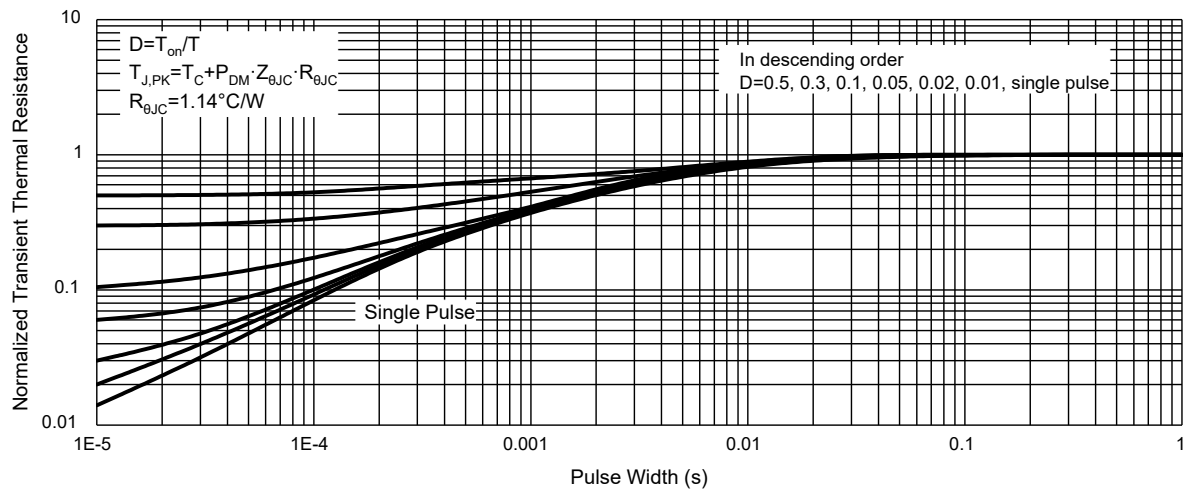


Fig. 8 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:2.5Kpcs/Reel

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